



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20082

Generic Copy

Issue Date: 08-May-2013

TITLE: Copper wire bond for IC Micro 8 package

PROPOSED FIRST SHIP DATE: 09-Aug-2013

AFFECTED CHANGE CATEGORY(S): Assembly Process - Package

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or <alan.garlington@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or <tomas.vajter@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

This FPCN is to notify customers of the planned qualification of Copper Wire (in place of Gold Wire) on the Micro 8 packages assembled at the Seremban, Malaysia assembly location. Reliability Qualification and full electrical characterization has now been completed on the designated package qualification vehicles.



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RELIABILITY DATA SUMMARY:

Reliability Test Results:

Test	Conditions	Results		
		<u>Qual A</u>	<u>Qual B</u>	<u>Qual C</u>
LP2951ACDMR2G Package = IC Micro 8	Reliability: S17183			
Preconditioning: MSL1 – 260 C				
Autoclave	Ta = 121C, RH = 100% Pressure = 15 PSIG; 96 Hrs	0/77	0/77	0/77
HAST	Ta = 130C, RH = 85% Pressure = 18.8 PSI; 192 Hrs	0/77	0/77	0/77
HTSL	Ta = 150 C, 1008 Hrs 2016 Hrs	0/77	0/77	0/77
		0/77	0/77	0/77
TC	Ta = -65C to +150C, 1000 Cycle 2000 Cycle	0/77	0/77	0/77
		0/77	0/77	0/77
Resistance to Solder Heat	JESD22 – B106 Temp = 260 C	0/30	0/30	0/30

ELECTRICAL CHARACTERISTIC SUMMARY:

There is no electrical characterization difference in products assembled with Copper Wire.

CHANGED PART IDENTIFICATION:

There will be no physical change with products assembled with Copper Wire in place of Gold Wire. Products listed on this FPCN will have a Marking Date Code representing Work Week 32, 2013 or later.

**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION # 20082****List of affected General Parts:**

LM258DMR2G	MC33164DM-5R2G	NCP3335ADMADJR2G
LM2903DMR2G	MC33178DMR2G	NCV2903DMR2G
LM2904ADMR2G	MC33202DMR2G	NCV2904DMR2G
LM2904DMR2G	MC33762DM-2525RG	NCV33064DM-5R2G
LM2904VDMR2G	MC33762DM-2828RG	NCV33161DMR2G
LM293DMR2G	MC33762DM-3030RG	NCV33202DMR2G
LM358DMR2G	MC34064DM-5R2G	NCV431AIDMR2G
LM393DMR2G	MC34161DMR2G	NCV431BVDMR2G
LP2951ACDM-3.0RG	MC34164DM-5R2G	TL431ACDMR2G
LP2951ACDM-3.3RG	NCP3335ADM150R2G	TL431AIDMR2G
LP2951ACDMR2G	NCP3335ADM180R2G	TL431BCDMR2G
LP2951CDM-3.0R2G	NCP3335ADM250R2G	TL431BIDMR2G
LP2951CDM-3.3R2G	NCP3335ADM280R2G	TL431BVDMR2G
LP2951CDMR2G	NCP3335ADM285R2G	TL431CDMR2G
MC33064DM-5R2G	NCP3335ADM300R2G	TL431IDMR2G
MC33161DMR2G	NCP3335ADM330R2G	
MC33164DM-3R2G	NCP3335ADM500R2G	